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DUAL 2-INPUT NAND GATE WITH OPEN-DRAIN OUTPUTS

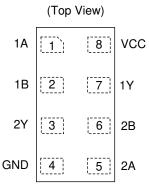
Description

The 74LVC2G38 is a dual, two input NAND gate with open-drain outputs. Both gates have open-drain outputs designed for operation over a power supply range of 1.65V to 5.5V. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down. Each gate performs the positive Boolean function

$$Y = \overline{A \bullet B}$$
 or $Y = \overline{A} + \overline{B}$

It is understood that the logical HIGH output level is a result of pull-up resistor.

Pin Assignments



X2-DFN2010-8 X2-DFN1410-8 X2-DFN1210-8

Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- Outputs Sink 24mA at Vcc = 3.3V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- Schmitt Trigger Action at all inputs makes the circuit tolerant for slower input rise and fall times. The hysteresis is typically 100mV at V_{CC} = 3.0V
- ESD Protection Exceeds JESD 22
 - 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Applications

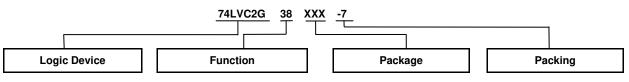
- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
 - PCs, Networking, Notebooks, Netbooks, PDAs
 - Tablet Computers, E-readers
 - Computer Peripherals, Hard Drives, CD/DVD ROMs
 - TVs, DVDs, DVRs, Set Top Boxes
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



Ordering Information (Note 4)



74 : Logic Prefix LVC: 1.65V to 5.5V Logic Family 2G: Dual Gate

2-Input NAND Gate With Open-Drain Outputs HD4: X2-DFN2010-8 HK3: X2-DFN1410-8 RA3: X2-DFN1210-8 -7: 7" Tape & Reel

	Package Package		Package	7" Tape and Reel (Note 6)		
Device	Code	(Note 5)	Size	Quantity	Part Number Suffix	
74LVC2G38HD4-7	HD4	X2-DFN2010-8	1.95mm x 1.0mm x 0.4mm 0.5mm lead pitch	5,000/Tape & Reel	-7	
74LVC2G38HK3-7	HK3	X2-DFN1410-8	1.35mm x 1.0mm x 0.35mm 0.4mm lead pitch	5,000/Tape & Reel	-7	
74LVC2G38RA3-7	RA3	X2-DFN1210-8	1.2mm x 1.0mm x 0.35mm 0.3mm lead pitch	5,000/Tape & Reel	-7	

Notes: 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

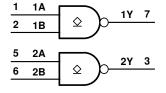
- 5. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at http://www.diodes.com/packageoutlines.html.

 6. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

Pin Descriptions

Pin Name	Pin No.	Description
1A	1	Data Input
1B	2	Data Input
2Y	3	Data Output (Open Drain)
GND	4	Ground
2A	5	Data Input
2B	6	Data Input
1Y	7	Data Output (Open Drain)
V _{CC}	8	Supply Voltage

Logic Diagram



Function Table

Inp	Output	
Α	Υ	
L	L	Z
L	Н	Z
Н	L	Z
Н	Н	L



Absolute Maximum Ratings (Notes 7 & 8)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
Vcc	Supply Voltage	-0.5 to +6.5	V
VI	Input Voltage	-0.5 to +6.5	V
Vo	Output Voltage -Active Mode	-0.5 to +6.5	V
Vo	Output Voltage Power Down Mode	-0.5 to +6.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current (Vo < 0)	-50	mA
lo	Continuous Output Current (Vo = 0 to 5.5V)	50	mA
Icc	Continuous Current Through V _{CC}	100	mA
I _{GND}	Continuous Current Through GND	-100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Notes:

- 7. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
- 8. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 9)

Symbol	Pa	Parameter				
V	Operation Voltage	Operating	1.65	5.5	٧	
V _{CC}	Operating Voltage	Data Retention Only	1.5	_	V	
VI	Input Voltage	•	0	5.5	V	
\/	Output Voltage Active Mode		0	5.5	V	
Vo	Output Voltage Power-Down Mode		0	5.5	V	
		V _{CC} = 1.65V	_	4		
	Lough ovel Output Current	V _{CC} = 2.3V	_	8	mA	
1		V _{CC} = 2.7V	_	12		
l _{OL}	Low-Level Output Current	V 2.0V	_	16		
		$V_{CC} = 3.0V$	_	24		
		V _{CC} = 4.5V	_	32		
Δt/ΔV	Input Transition Pipe or Fall Pate	V _{CC} = 1.65V to 2.7V	_	20	no/\/	
ΔυΔν	Input Transition Rise or Fall Rate	V _{CC} = 2.7V to 5.5V	_	10	ns/V	
TA	Operating Free-Air Temperature		-40	+125	°C	

Note: 9. Unused inputs should be held at V_{CC} or Ground.



Electrical Characteristics (All typical values are at $T_A = +25$ °C)

		T . 0 !::	.,	-40	°C to +8	5°C	-40°C to	+125°C	11	
Symbol	Parameter	Test Conditions	V _{cc}	Min	Тур.	Max	Min	Max	Unit	
			$V_{CC} = 1.65V \text{ to } 1.95V$	0.65 x V _{CC}		_	0.65 x V _{CC}	_		
	High-Level		V _{CC} = 2.3V to 2.7V	1.7	-	_	1.7	_	1 ,,	
V_{IH}	Input Voltage	_	V _{CC} = 2.7V to 3.6V	2.0	_	_	2.0	_	V	
			$V_{CC} = 4.5V \text{ to } 5.5V$	0.7 x V _{CC}	_	_	0.7 x V _{CC}	_		
			$V_{CC} = 1.65V \text{ to } 1.95V$	_		0.35 x V _{CC}	1	0.35 x V _{CC}		
\/	Low-Level		$V_{CC} = 2.3V \text{ to } 2.7V$	_		0.7	1	0.7	V	
V_{IL}	Input Voltage	_	$V_{CC} = 2.7V \text{ to } 3.6V$	_	1	0.8	1	0.8	V	
			$V_{CC} = 4.5V \text{ to } 5.5V$	_		0.3 x V _{CC}	1	0.3 x V _{CC}		
		I _{OL} = 100μA	1.65V to 5.5V	_	0	0.1	1	0.1		
			$I_{OL} = 4mA$	1.65V	_	0.08	0.45	_	0.7	
	Low-Level	$I_{OL} = 8mA$	2.3V	_	0.14	0.3	_	0.45		
V_{OL}	Output	$I_{OL} = 12mA$	2.7V	_	0.19	0.4	_	0.6	V	
	Voltage	$I_{OL} = 16mA$	3V	_	0.25	0.4	_	0.6		
		$I_{OL} = 24mA$	ον	_	0.37	0.55	_	0.8		
		$I_{OL} = 32mA$	4.5V	_	0.43	0.55	1	0.8		
II	Input Current	V _I = 5.5V or GND	0V to 5.5V	_	± 0.1	±5	_	± 20	μΑ	
l _{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5V$	0V	_	± 0.1	±10	_	±20	μА	
Icc	Supply Current	$V_I = 5.5V$ or GND $I_O = 0A$	1.65V to 5.5V	_	0.1	10	-	40	μΑ	
ΔI _{CC}	Additional Supply Current	One input at V _{CC} – 0.6V Other inputs at V _{CC} or GND	2.3V to 5.5V	_	5	500	_	5,000	μА	
Cı	Input Capacitance	V _I = V _{CC} or GND	3.3V	_	2.5	_	_	_	рF	



Operating Characteristics

Parameter		Test Conditions	V _{cc} = 1.8V Typ.	V _{CC} = 2.5V Typ.	V _{cc} = 3.3V Typ.	V _{cc} = 5V Typ.	Unit
$C_{\sf pd}$	Power Dissipation Capacitance	f = 10MHz	6	7	7	9	pF

Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Тур.	Max	Unit
		X2-DFN2010-8		_	313	_	
θ_{JA}	Thermal Resistance Junction- to-Ambient	X2-DFN1410-8	(Note 10)	_	321	_	°C/W
	to-Ambient	X2-DFN1210-8		_	395		
	T. 15	X2-DFN2010-8		_	145	_	
θ_{JC}	Thermal Resistance Junction-	X2-DFN1410-8	(Note 10)	_	166		°C/W
l ^t	to-Case	X2-DFN1210-8		_	236	_	1

Note: 10. Test condition for each package type: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

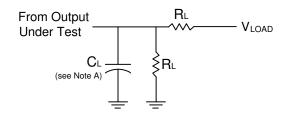
Switching Characteristics

Typical Values at $T_A = +25$ °C and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V. See Figure 1.

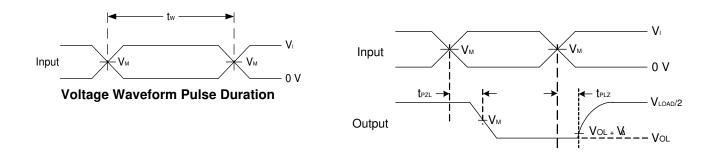
P	From	То	V	T _A	= -40°C to +85	5°C	T _A = -40°C	to +125°C	11
Parameter	Input	Output	V _{CC}	Min	Тур	Max	Min	Max	Unit
			1.8V ± 0.15V	1.2	3.0	8.6	1.2	10.8	
			2.5V ± 0.2V	0.7	1.8	4.8	0.7	6.0	
t_{PZL}	A or B	Υ	2.7V	0.7	2.5	4.4	0.7	5.5	ns
			3.3V ± 0.3V	0.7	2.1	4.1	0.7	5.2]
			5.0V ± 0.5V	0.5	1.5	3.3	0.5	4.2]
			1.8V ± 0.15V	1.2	3.0	8.6	1.2	10.8	
			2.5V ± 0.2V	0.7	1.8	4.8	0.7	6.0]
t _{PLZ} A or B	Y	2.7V	0.7	2.5	4.4	0.7	5.5	ns	
			$3.3V \pm 0.3V$	0.7	2.1	4.1	0.7	5.2	
			5.0V ± 0.5V	0.5	1.5	3.3	0.5	4.2	



Parameter Measurement Information



V	Inp	outs	V	V		RL	V.
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	V _{LOAD} C _L		V Δ
1.8V ± 0.15V	V _{CC}	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	1kΩ	0.15V
2.5V ± 0.2V	V _{CC}	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V ± 0.3V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5.0V ± 0.5V	V _{CC}	≤2.5ns	V _{CC} /2	2 x V _{CC}	50pF	500Ω	0.3V



Voltage Waveforms Inverting and Non Inverting Outputs

Figure 1. Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10MHz.

C. Inputs are measured separately one transition per measurement.



Marking Information

(Top View)

<u>XX</u>

XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week

X : Internal Code

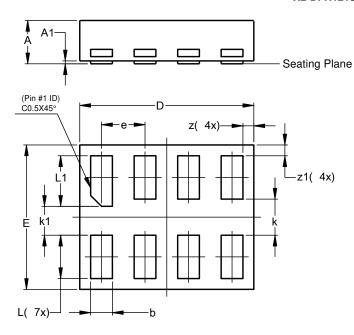
Part Number	Package	Identification Code
74LVC2G38HD4-7	X2-DFN2010-8	9M
74LVC2G38HK3-7	X2-DFN1410-8	9N
74LVC2G38RA3-7	X2-DFN1210-8	9P



X2-DFN1210-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1210-8

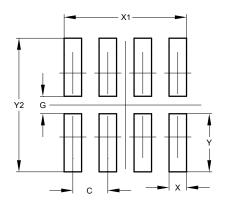


	X2-DFN1210-8								
Dim	Min	Max	Тур						
Α	-	0.35	0.30						
A 1	0	0.03	0.02						
b	0.10	0.20	0.15						
D	1.15	1.25	1.20						
Е	0.95	1.05	1.00						
е	-	-	0.30						
k	-	-	0.25						
k1	-	-	0.20						
L	0.25	0.35	0.30						
L1	0.30	0.40	0.35						
Z	0.050	0.100	0.075						
z1	0.050	0.100	0.075						
All I	All Dimensions in mm								

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1210-8



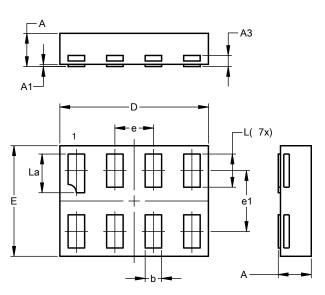
Dimensions	Value (in mm)
С	0.300
G	0.150
X	0.150
X1	1.050
Υ	0.500
Y1	1.150



X2-DFN1410-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1410-8

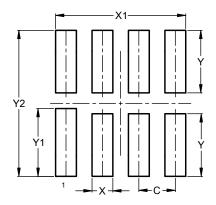


X2-DFN1410-8				
Dim	Min	Max	Тур	
Α	0.30	0.35	0.33	
A1	0.00	0.03	0.02	
А3		-	0.10	
b	0.12	0.20	0.15	
D	1.30	1.40	1.35	
Е	0.95	1.05	1.00	
е			0.35	
e1			0.55	
L	0.27	0.35	0.30	
L1	0.32	0.40	0.35	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1410-8



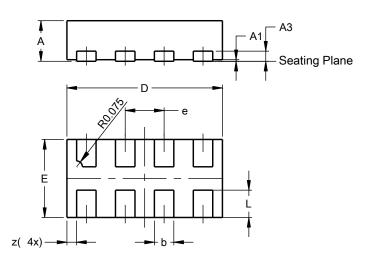
Dimensions	Value (in mm)
С	0.350
Х	0.200
X1	1.250
Υ	0.600
Y1	0.650
Y2	1.400



X2-DFN2010-8 Package Outline Dimensions

 $\label{please} Please see \ http://www.diodes.com/package-outlines.html \ for the \ latest \ version.$

X2-DFN2010-8

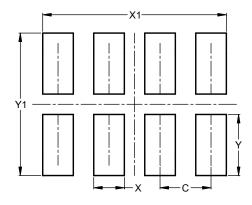


X2-DFN2010-8				
Dim	Min	Max	Тур	
Α		0.40		
A 1	0.00	0.05	0.02	
A3			0.13	
b	0.20	0.30	0.25	
D	1.950	2.05	2.00	
Е	0.95	1.05	1.00	
е			0.50	
L	0.30	0.40	0.35	
Z			0.125	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN2010-8



Dimensions	Value (in mm)
С	0.500
X	0.300
X1	1.800
Y	0.600
V1	1 400



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